



Product Change Notification

Change Notification #: 115610 - 00
Change Title: Intel® Server Chassis P4000XXSFDR,
PCN 115610-00, Label,
Update regulatory label to include
BSMI RoHS text logo
Date of Publication: June 20, 2017

Key Characteristics of the Change:
Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	Jul 07, 2017
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following changes on the products listed below: Intel® Server Chassis P4000XXSFDR

1. Update the packaging regulatory label, by replacing the BSMI logo with the new version that includes RoHS text to the label. Please see Figure-1 and Figure-2 below for details.



Figure-1: Pre-Change



Figure-2: Post-change

2. Update the regulatory label, by replacing the BSMI logo with the new version that includes RoHS text to the label. Please see Figure-3 and Figure-4 below for details.



Figure-3: Pre-Change



Figure-4: Post-Change

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
R1208WT2GSR	943894	H71611-003	H71611-004

PCN Revision History:

Date of Revision:

June 20, 2017

Revision Number:

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Reason:

Originally Published PCN



Product Change Notification

115610 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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